



High performance Schottky diodes based on indium-gallium-zinc-oxide

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High performance Schottky diodes based on indium-gallium-zinc-oxide

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Indium-gallium-zinc-oxide (IGZO) Schottky diodes exhibit excellent performance in comparison with conventional devices used in future flexible high frequency electronics. In this work, a high performance Pt IGZO Schottky diode was presented by using a new fabrication process. An argon/oxygen mixture gas was introduced during the deposition of the Pt layer to reduce the oxygen deficiency at the Schottky interface. The diode showed a high barrier height of 0.92 eV and a low ideality factor of 1.36 from the current–voltage characteristics. Even the radius of the active area was 0.1 mm, and the diode showed a cut-off frequency of 6 MHz in the rectifier circuit. Using the diode as a demodulator, a potential application was also demonstrated in this work. © 2016 American Vacuum Society. [<http://dx.doi.org/10.1116/1.4945102>]

I. INTRODUCTION

Indium-gallium-zinc-oxide (IGZO) is an emerging n type metal oxide semiconductor which has been widely used in display industries as the active material in back-panel driving units.^{1,2} It has been regarded as an alternative of amorphous silicon due to its relatively high mobility ($\sim 10 \text{ cm}^2 \text{ V}^{-1} \text{ s}^{-1}$), good visible light transparency, high uniformity over large areas, and compatibility with low temperature deposition techniques.³ However, most of the studies on IGZO to date have been based on thin film transistors (TFTs), which normally operated at low frequencies.⁴ As the operation frequencies of TFTs are limited by the mobility, the channel length, and the overlay between source/drain and gate electrodes, in order to realize gigahertz electronics by using IGZO TFTs, the scale of the active area needs to be reduced to submicron, which is difficult for photolithography processes.⁵ In recent years, IGZO Schottky diodes have drawn much attention due to their advantages in high speed operations.^{6–10} In 2015, the cut-off frequencies of IGZO Schottky diodes were improved to 16 GHz,⁹ which covers most of daily used frequency bands. Several potential applications have also been demonstrated in the last few years.^{7,11} However, due to the nature of metal oxide semiconductors, the properties of the Schottky contacts highly depend on the oxygen contents at the metal–semiconductor interfaces.^{12–14} Postannealing treatment is one of the methods to improve the rectification properties.⁶ Another method is to create an oxygen rich layer at the Schottky interface by introducing a pretreatment such as oxygen plasma etching or UV ozone oxidation on the Schottky contacts.¹² For ZnO Schottky diodes, the interface properties can be improved by using oxidized noble contacts.^{13,14} It is found that the inclusion of

oxygen during the deposition of the noble metal is able to reduce the defects caused by oxygen vacancies at the interface between metal and single crystalline ZnO.^{13,14} Despite the amorphous structure, it is plausible that such techniques may also be used to improve the interface properties of IGZO Schottky diodes.

In this work, we have successfully presented the high-performance Pt-IGZO Schottky diodes fabricated at room temperature (RT) by introducing oxygen during the deposition of Pt without any postannealing treatment. The properties of the diodes have been analyzed in terms of current–voltage characteristics, capacitance–voltage characteristics, and frequency response. We also demonstrated a simple crystal radio system by using the Pt-IGZO Schottky diode as the demodulator.

II. EXPERIMENT

Si-SiO₂ wafers were used as substrates in this work. The substrates were degreased by supersonic cleaning in deionized water, acetone, and methanol, then dried with nitrogen and placed in UV/ozone chamber for 30 min. Pt electrodes of 50 nm-thick were deposited by using RF sputtering at 80 W in pure Ar (devices A and B) and Ar/3% O₂ mixture gas (device C). IGZO (In₂O₃:Ga₂O₃:ZnO = 1:1:2) was sputtered at 80 W for 50 nm in Ar (devices A and C) and Ar/3% O₂ mixture gas (device B). The Al top electrodes were deposited by using thermal evaporation and defined by shadow masks. The current–voltage (J–V) characteristics were measured by using Agilent E5260B Semiconductor analyser at RT in dark. Agilent E4980A LCR meter was used to measure the capacitance–voltage (C–V) characteristics. The frequency response of the IGZO Schottky diodes was measured by Agilent 34401A digital multimeter, and the AC signal was generated by HP 8116A signal generator.

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85 **III. RESULTS AND DISCUSSION**

86 The structure of the diode is shown as the inset in Fig. 1(a).
 87 The active area of the device was determined by the top Al
 88 electrode. The radius of the contact equaled 0.1 mm. In Fig.
 89 1(a), the J-V characteristics of devices A, B, and C are shown.
 90 According to the thermionic emission theory,¹⁵ the J-V
 91 characteristics of the Schottky diode can be described as

$$J = J_0 \left\{ \exp \left[\frac{q(V - JR_s)}{nk_B T} \right] - 1 \right\}$$

$$= A^* T^2 \exp \left(-\frac{q\phi_b}{k_B T} \right) \left\{ \exp \left[\frac{q(V - JR_s)}{nk_B T} \right] - 1 \right\}, \quad (1)$$

92 where J_0 is called the saturation current density, A^* is the
 93 Richardson constant which equals $41 \text{ A cm}^{-2} \text{ K}^{-2}$ for
 94 IGZO,⁶ k_B is the Boltzmann constant, T is the temperature,
 95 ϕ_b represents the barrier height of the diode, R_s is the series
 96 resistance, and n is defined as the ideality factor. By fitting
 97 the J-V curves according to Eq. (1) at low biases where V
 98 $\gg JR_s$, the barrier height, on/off ratio, and ideality factor can
 99 be obtained, which are shown in Table I. For device A, it
 100 showed a relatively low barrier height of 0.52 eV and an
 101 ideality factor of 2.50. The rectification ratio at $\pm 1 \text{ V}$ was
 102 only 10^3 . For device B, the on/off ratio became 2.0×10^4 ,
 103 and the ideality factor dropped to 1.56. Compared with de-
 104 vice A, device B showed a higher barrier height of 0.72 eV.
 105 When depositing Pt with 3% O_2 , device C exhibited a better
 106 performance compared with devices A and B. The barrier
 107 height was found to be 0.92 eV, which agreed well with the
 108 estimation if assuming the work function of Pt is 5.4 eV and
 109 the electron affinity of IGZO is 4.5 eV.⁶ The ideality factor
 110 was also close to unity, which suggested that the barrier
 111 height was uniform at the interface. The on/off ratio was
 112 found to be higher than 10^6 .

113 Figure 1(b) shows the C-V characteristics of devices B
 114 and C. The relation between the diode capacitance and the
 115 applied bias can be described by

$$C^{-2} = \frac{2(V_{bi} - V)}{q\epsilon_0\epsilon_r N_{bg}}, \quad (2)$$

116 where V_{bi} is the built-in voltage, ϵ_0 is the vacuum permittiv-
 117 ity, ϵ_r is the relative dielectric constant of IGZO, and N_{bg} is

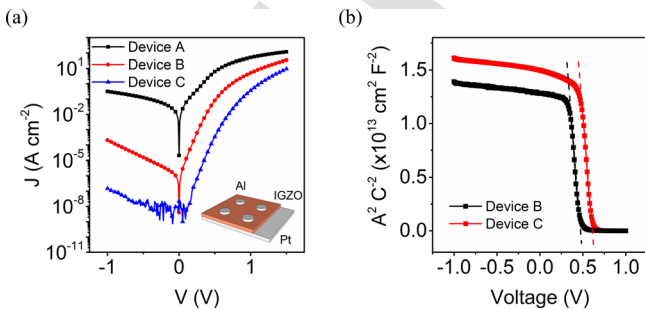


FIG. 1. (Color online) (a) J-V characteristics of Pt-IGZO Schottky diodes with different fabrication conditions. The inset shows the structure of the diodes. (b) C^{-2} -V characteristics of devices B and C. The fittings were shown by the dashed lines.

TABLE I. Effects of oxygen during sputtering.

Pt IGZO	Ar Ar	Ar Ar + 3% O_2	Ar + 3% O_2 Ar
n	2.50	1.56	1.36
ϕ_b	0.52 eV	0.72 eV	0.92 eV
On/off ratio at $\pm 1 \text{ V}$	103	2.0×10^4	2.4×10^6
R_{tot} at 1.5 V	40.27 eV_λ	$138.54 \text{ eV}_\lambda$	$507.21 \text{ eV}_\lambda$
V_{bi}	N/A	0.46 V	0.60 V
N_{bg}	N/A	$3.50 \times 10^{18} \text{ cm}^{-3}$	$4.05 \times 10^{18} \text{ cm}^{-3}$

called the background doping density. By assuming the
 diodes were fully depleted at -1 V , the relative dielectric
 constant of IGZO was found to be 15 for device B and 14 for
 device C. The differences might be caused by the different
 oxygen content in the IGZO layer. By using Eq. (2), the
 extracted parameters are shown in Table I. It is found that
 for device B, the built-in voltage was 0.46 V and the back-
 ground doping density was $3.50 \times 10^{18} \text{ cm}^{-3}$. Device C
 showed a higher built-in voltage of 0.60 V and a background
 doping density of $4.05 \times 10^{18} \text{ cm}^{-3}$.

The oxygen content at the interface is vital for metal
 oxide semiconductors to form high-quality Schottky junc-
 tions.^{10,12-14} Allen *et al.* have reported that for ZnO
 Schottky diodes, oxygen deficiency can induce defects at the
 interface and cause Fermi level pinning.^{13,14} This explains
 why device A, where Pt and IGZO were deposited in pure
 Ar, exhibited the lowest barrier height and the highest ideal-
 ity factor. Introducing 3% O_2 during the deposition of IGZO
 serves to reduce the number of dangling bonds at the
 Pt-IGZO interface and may unintentionally oxidize the Pt
 surface, thus improving the rectification properties of the
 diode.

An alternative solution is to intentionally create an
 oxygen-rich phase at the Pt-IGZO interface. It is found that
 device C showed the highest barrier height, the highest
 on/off ratio, and the lowest ideality factor among the three
 devices. In the C-V measurements, it also showed a higher
 built-in voltage than the value of device B, which suggests
 that depositing Pt in Ar/ O_2 mixture gas helps to reduce oxy-
 gen deficiencies and thus contributes to a better Schottky
 junction.

The current-voltage-temperature characteristics of device
 C are shown in Figs. 2(a) and 2(b). The linear dependency of
 $\ln(J_0/T^2)$ on T^{-1} indicates that the thermionic emission dom-
 inates the current transport in the diode. The barrier height
 decreases with increasing temperature, which may be due to
 the inhomogeneities at the Schottky interface.¹⁶ Assuming
 these inhomogeneities in barrier height are Gaussian distrib-
 uted,¹⁶ the mean barrier height is found to be 1.46 eV with a
 standard deviation of 0.16 eV. The potential fluctuation at
 the Schottky junction may be caused by the amorphous
 structure of IGZO, the grain boundaries, and the different
 crystalline orientations of the Pt layer. An additional thermal
 annealing step could serve to minimize these fluctuations.

The rectification properties of device C at different fre-
 quencies are shown in Fig. 3. The inset shows the setup of

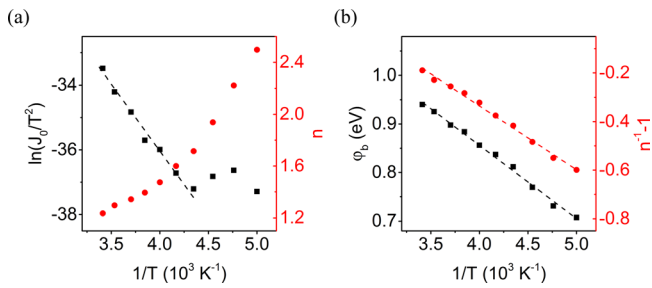


FIG. 2. (Color online) (a) Richardson plot (black dots) and ideality factor (red dots) as a function of $1/T$. (b) Barrier height (black dots) and $(n^{-1}-1)$ shown as red dots at different temperatures.

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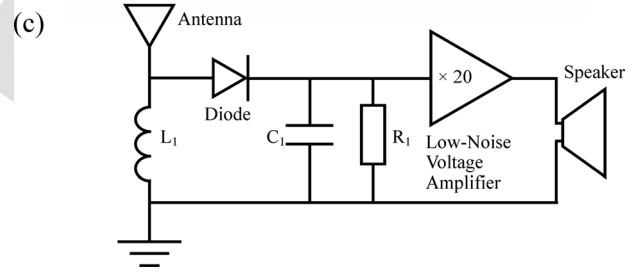
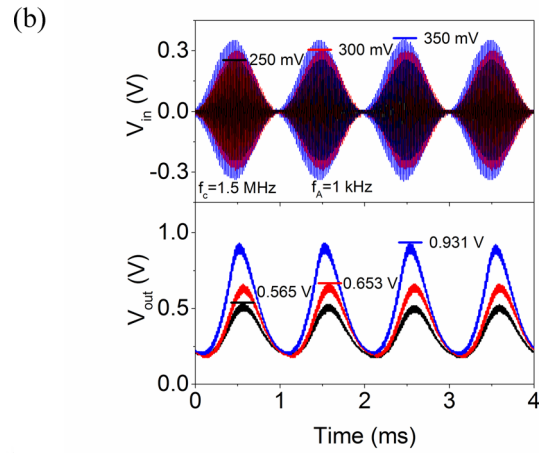
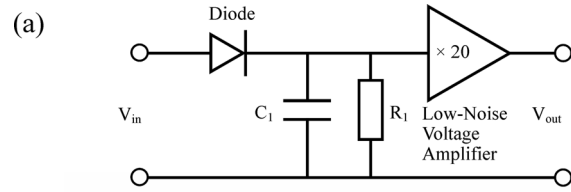


FIG. 4. (Color online) (a) Schematic of the demodulation test setup. C_1 equals 1 nF and R_1 is 12 k Ω . The demodulation signal is amplified 20 times by a low-noise voltage amplifier. (b) Input waveforms and output waveforms. The carrier frequency is 1.5 MHz, and the information frequency is 1 kHz. (c) Schematic of the crystal radio receiver by using the IGZO Schottky diode.

amplitude of the AM signal was set to be 250, 300, and 350 mV, respectively. The peak voltage of the corresponding rectified signals are found to be 0.565, 0.653, and 0.931 V, respectively. Figure 4(c) shows a potential application, namely, an AM radio receiver, using the IGZO Schottky diode as the demodulator. A 5 m-long metal wire was used as the antenna to receive the radio signal (Gold at 1.458 MHz in Manchester). The input AM signal was rectified by the IGZO Schottky diode. The rectified AM signal was converted to the audio signal with a cut-off frequency of 13 kHz through the low-pass filter and amplified 20 times by an SR560 low noise voltage amplifier. Then, the amplified audio signal was connected to a speaker. The demonstration of the fully functional radio receiver is shown in supplementary video.¹⁷

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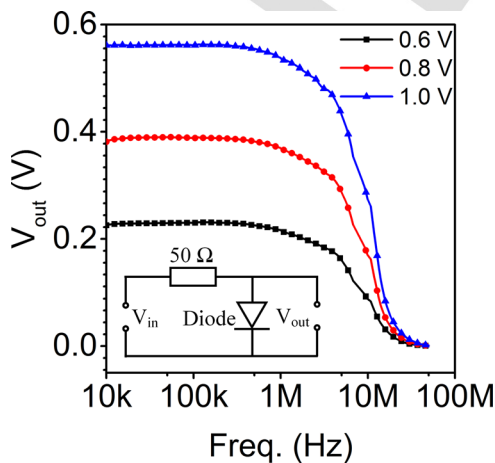


FIG. 3. (Color online) Output voltage as a function of frequency at input signal voltages. The peak amplitudes of the input signals were 0.6, 0.8, and 1.0 V, respectively. The inset shows the diagram of the rectifier circuit.

IV. SUMMARY AND CONCLUSIONS

In this work, we proposed an alternative fabrication process to improve the rectification properties of Pt-IGZO Schottky diodes. The J-V and C-V characteristics showed superior performance to the values obtained from the devices

210 fabricated with the conventional processes. The role of oxy-
 211 gen in the formation of the Schottky barrier has been eluci-
 212 dated and could be further understood by the use of
 213 quantitative analytical methods such as secondary ion mass
 214 spectroscopy. The cut-off frequency of the diode was found
 215 to be around 6 MHz, which could be further improved by
 216 adopting the high-frequency coplanar waveguide design.
 217 We also demonstrated an AM radio receiver by using the
 218 Pt-IGZO Schottky diode as the demodulator. These results
 219 shed light on potential applications of IGZO Schottky diodes.

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